

Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Low V_F and Low Leakage Current
- Patented Interlocking Clip Design for High Surge Current Capacity
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at <https://www.diodes.com/products/automotive/automotive-products/>.**
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability. <https://www.diodes.com/quality/product-definitions/>**

Mechanical Data

- Package: PowerDI[®]123
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.01 grams (Approximate)

PowerDI123



Top View

Ordering Information (Note 4)

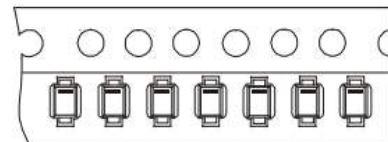
Part Number	Package	Packing	
		Qty.	Carrier
DFLS230LH-7	PowerDI123	3000	Tape & Reel

- Notes:
- EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 - See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



F03H = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: J = 2022)
 M = Month (ex: 9 = September)



Date Code Key

Year	2005	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031
Code	S	J	K	L	M	N	O	P	R	S	T
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Forward Current	I _{F(AV)}	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	75	A

Thermal Characteristics

Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point (Note 5)	R _{θJS}	—	6	°C/W
Operating Temperature Range	T _J	-65 to +150		°C
Storage Temperature Range	T _{STG}	-65 to +150		°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	30	—	—	V	I _R = 200μA
Forward Voltage	V _F	—	—	0.45 0.375	V	I _F = 2A, T _J = +25°C I _F = 2A, T _J = +125°C
Leakage Current (Note 6)	I _R	—	—	0.200 15	mA	V _R = 30V, T _J = +25°C V _R = 30V, T _J = +100°C
Total Capacitance	C _T	—	85	—	pF	V _R = 10V, f = 1.0MHz

Notes: 5. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
6. Short duration pulse test used to minimize self-heating effect.

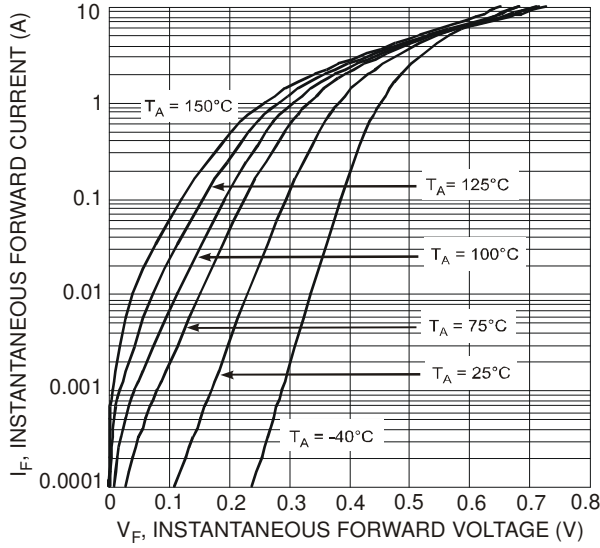


Fig. 1 Typical Forward Characteristics

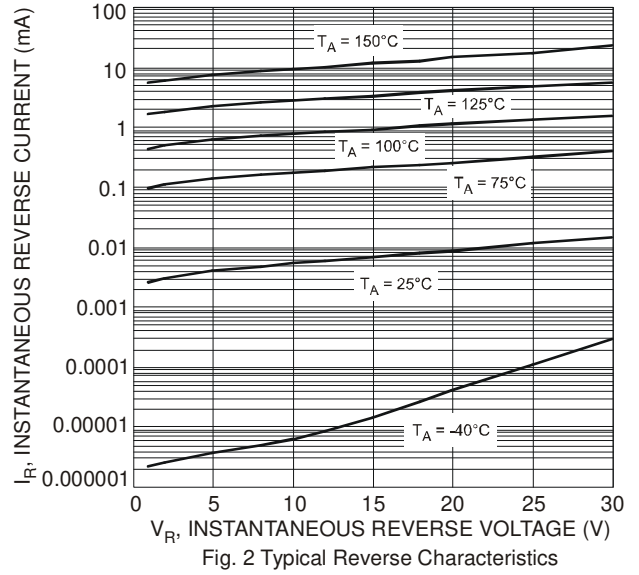


Fig. 2 Typical Reverse Characteristics

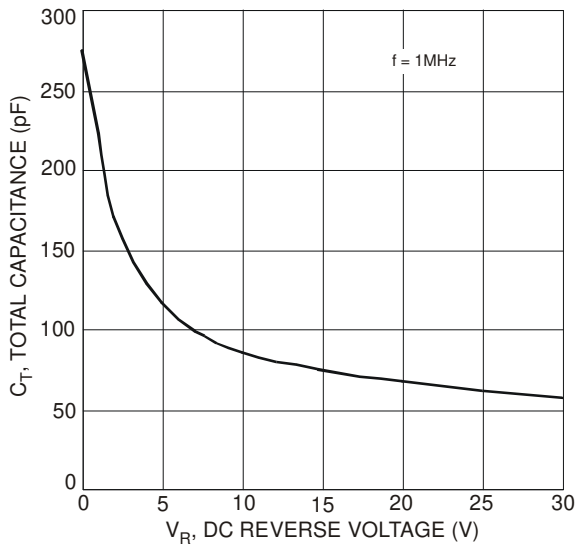


Fig. 3 Total Capacitance vs. Reverse Voltage

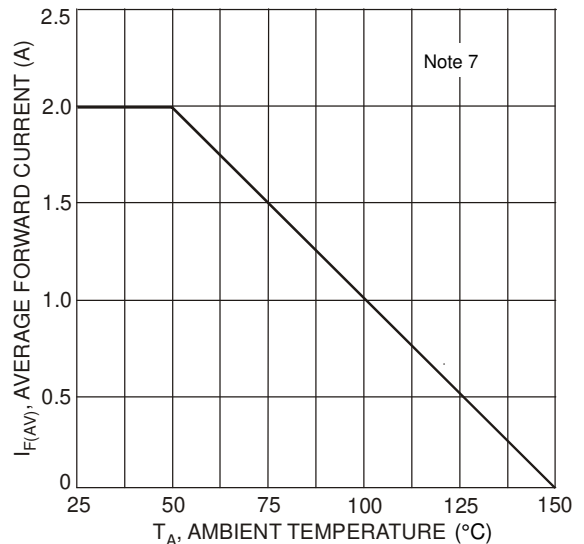


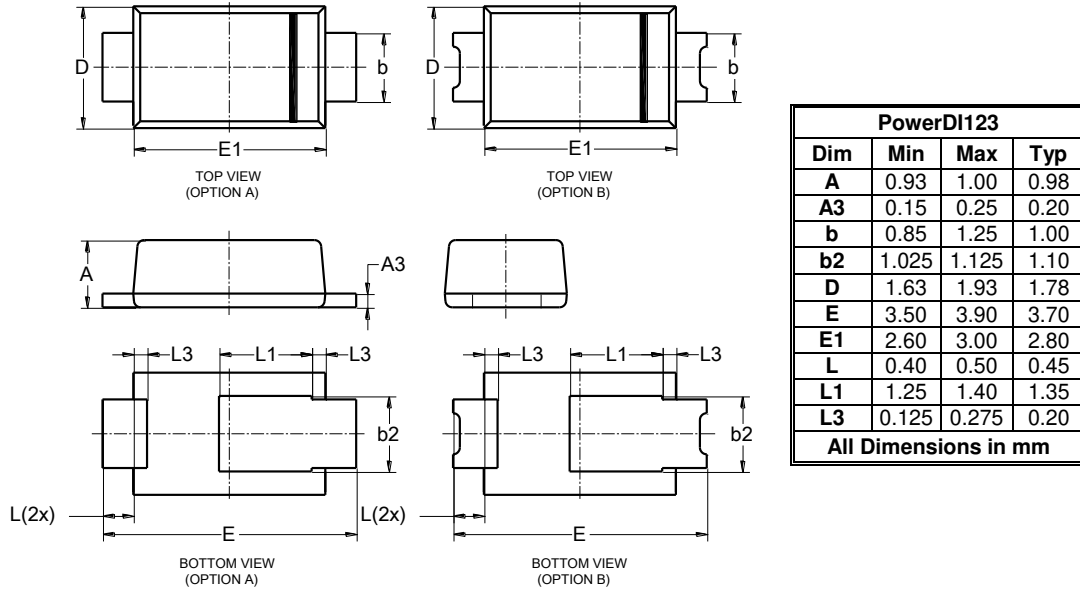
Fig. 4 Forward Current Derating Curve

Note: 7. Part mounted on FR-4 board with 2oz., minimum recommended copper pad layout which can be found on our website at <http://www.diodes.com/package-outlines.html>. $T_A = +25^\circ\text{C}$.

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

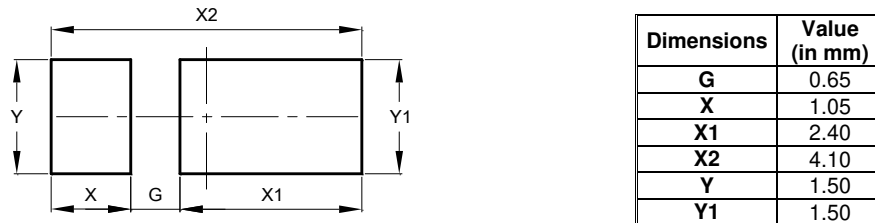
PowerDI123



Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123



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